

February 1998 Revised July 2000

74VHC161284 IEEE 1284 Transceiver

General Description

The VHC161284 contains eight bidirectional data buffers and eleven control/status buffers to implement a full IEEE 1284 compliant interface. The device supports the IEEE 1284 standard and is intended to be used in Extended Capabilities Port mode (ECP). The pinout allows for easy connection from the Peripheral (A-side) to the Host (cable side).

Outputs on the cable side can be configured to be either open drain or high drive (\pm 14 mA). The pull-up and pull-down series termination resistance of these outputs on the cable side is optimized to drive an external cable. In addition, all inputs (except HLH) and outputs on the cable side contain internal pull-up resistors connected to the V_{CC} supply to provide proper termination and pull-ups for open drain mode.

Outputs on the Peripheral side are standard LOW-drive CMOS outputs. The DIR input controls data flow on the A_1-A_8/B_1-B_8 transceiver pins.

Features

- Supports IEEE 1284 Level 1 and Level 2 signaling standards for bidirectional parallel communications between personal computers and printing peripherals
- Replaces the function of two (2) 74ACT1284 devices
- All inputs have hysteresis to provide noise margin
- B and Y output resistance optimized to drive external cable
- B and Y outputs in high impedance mode during power down
- Inputs and outputs on cable side have internal pull-up resistors
- Flow-through pin configuration allows easy interface between the Peripheral and Host

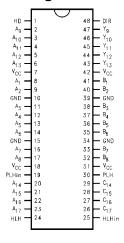
Ordering Code:

Ordering Number	Package Number	Package Description
74VHC161284MEA	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300 Wide
74VHC161284MTD	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Surface mount packages are also available on Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

Connection Diagram



Pin Descriptions

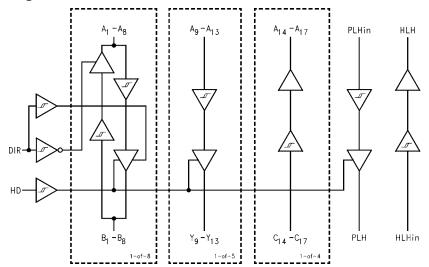
Pin Names	Description
HD	HIGH Drive Enable Input (Active HIGH)
DIR	Direction Control Input
A ₁ -A ₈	Inputs or Outputs
B ₁ -B ₈	Inputs or Outputs
A ₉ -A ₁₃	Inputs
Y ₉ -Y ₁₃	Outputs
A ₁₄ -A ₁₇	Outputs
C ₁₄ –C ₁₇	Inputs
PLH _{IN}	Peripheral Logic HIGH Input
PLH	Peripheral Logic HIGH Output
HLH _{IN}	Host Logic HIGH Input
HLH	Host Logic HIGH Output

Truth Table

Inp	uts	Outputs			
DIR	HD	Outputs			
L	L	B ₁ –B ₈ Data to A ₁ –A ₈ , and			
		$A_9 - A_{13}$ Data to $Y_9 - Y_{13}$ (Note 1)			
		C ₁₄ –C ₁₇ Data to A ₁₄ –A ₁₇			
		PLH Open Drain Mode			
L	Н	B ₁ -B ₈ Data to A ₁ -A ₈ , and			
		A ₉ -A ₁₃ Data to Y ₉ -Y ₁₃			
		C ₁₄ -C ₁₇ Data to A ₁₄ -A ₁₇			
Н	L	A ₁ -A ₈ Data to B ₁ -B ₈ (Note 2)			
		A ₉ -A ₁₃ Data to Y ₉ -Y ₁₃ (Note 1)			
		C ₁₄ -C ₁₇ Data to A ₁₄ -A ₁₇			
		PLH Open Drain Mode			
Н	Н	A ₁ -A ₈ Data to B ₁ -B ₈			
		A ₉ -A ₁₃ Data to Y ₉ -Y ₁₃			
		C ₁₄ -C ₁₇ Data to A ₁₄ -A ₁₇			

Note 1: Y₉–Y₁₃ Open Drain Outputs Note 2: B₁–B₈ Open Drain Outputs

Logic Diagram



Absolute Maximum Ratings(Note 3) **Recommended Operating Conditions** Supply Voltage

-0.5V to +7.0V V_{CC}

Input Voltage (V_I) (Note 4) A₁-A₁₃, PLH_{IN}, DIR, HD -0.5V to $V_{CC} + 0.5V$ B₁-B₈, C₁₄-C₁₇, HLH_{IN} -0.5V to +5.5V (DC)

B₁-B₈, C₁₄-C₁₇, HLH_{IN} -2.0V to + 7.0V * *40 ns Transient

Output Voltage (V_O)

A₁-A₈, A₁₄-A₁₇, HLH -0.5V to $V_{CC} + 0.5V$ B₁-B₈, Y₉-Y₁₃, PLH -0.5V to +5.5V (DC) B₁-B₈, Y₉-Y₁₃, PLH -2.0V to +7.0V*

*40 ns Transient

DC Output Current (I_O)

±25 mA A_1 – A_8 , HLH B₁-B₈, Y₉-Y₁₃ $\pm 50 \text{ mA}$ PLH (Output LOW) 84 mA PLH (Output HIGH) -50 mA

Input Diode Current (I_{IK}) (Note 4)

DIR, HD, A₉–A₁₃,

PLH, HLH, C₁₄-C₁₇ -20 mA

Output Diode Current (I_{OK})

±50 mA A₁-A₈, A₁₄-A₁₇, HLH

 B_1-B_8 , Y_9-Y_{13} , PLH -50 mA

DC Continuous V_{CC} or

±200 mA **Ground Current**

-65°C to + 150°C Storage Temperature

ESD (HBM) Last Passing

2000V

Supply Voltage

4.5V to 5.5V V_{CC} DC Input Voltage (V_I) 0V to V_{CC} Open Drain Voltage (V_O) 0V to 5.5V Operating Temperature (T_A) -40°C to + 85°C

Note 3: Absolute Maximum continuos ratings are those values beyond which damage to the device may occur. Exposure to these indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: Either voltage limit or current limit is sufficient to protect inputs.

DC Electrical Characteristics

Symbol	Parame	ter	V _{CC}	T _A = -40°C to +85°C Guaranteed Limits	Units	Conditions
V _{IK}	Input Clamp Diode Voltage		3.0	-1.2	V	
V _{IH}	Minimum HIGH Level Input Voltage	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.7 V _{CC}		
		B _n	4.5 – 5.5	2.0	V	
		C _n	4.5 – 5.5	2.3	V	
		HLH _{IN}	4.5 – 5.5	2.6		
V _{IL}	Maximum LOW Level Input Voltage	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.3 V _{CC}		
		B _n	4.5 – 5.5	0.8	V	
		C _n	4.5 – 5.5	0.8	v	
		HLH _{IN}	4.5 – 5.5	1.6		
ΔVT	Minimum Input Hysteresis	A _n , PLH _{IN} , DIR, HD	4.5 – 5.5	0.4		V _T + –V _T –
		B _n	4.5 – 5.5	0.4	V	$V_T^+ - V_T^-$
		C _n	5.0	0.8		$V_{T}^{+} - V_{T}^{-}$
		HLH _{IN}	5.0	0.3		$V_{T}^{+} - V_{T}^{-}$
V _{OH}	Minimum HIGH Level Output Voltage	A _n , HLH	4.5	4.4		$I_{OH} = -50 \mu A$
			4.5	3.8	V	$I_{OH} = -8 \text{ mA}$
		B _n , Y _n	4.5	3.73	, v	$I_{OH} = -14 \text{ mA}$
		PLH	4.5	4.45		$I_{OH} = -500 \mu A$

DC Electrical Characteristics (Continued)

Symbol	Parameter		v _{cc}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	Units	Conditions
•			(V)	Guaranteed Limits		
V _{OL}	Maximum LOW Level Output Voltage	A _n , HLH	4.5	0.1		$I_{OL} = 50 \mu A$
			4.5	0.44	V	$I_{OL} = 8 \text{ mA}$
		B _n , Y _n	4.5	0.77	l *	I _{OL} = 14 mA
		PLH	4.5	0.7		$I_{OL} = 84 \text{ mA}$
RD	Maximum Output Impedance	B ₁ -B ₈ , Y ₉ -Y ₁₃	5.0	55	Ω	(Note 5)(Note 6)
	Minimum Output Impedance	B ₁ -B ₈ , Y ₉ -Y ₁₃	5.0	35	Ω	(Note 5)(Note 6)
RP	Maximum Pull-Up Resistance	B ₁ -B ₈ , Y ₉ -Y ₁₃ , C ₁₄ -C ₁₇	5.0	1650	Ω	
	Minimum Pull-Up Resistance	B ₁ -B ₈ , Y ₉ -Y ₁₃ , C ₁₄ -C ₁₇	5.0	1150	Ω	
I _{IH}	Maximum Input Current in HIGH State	A ₉ -A ₁₃ , PLH _{IN} , HD, DIR, HLH _{IN}	5.5	1.0	цΑ	$V_{I} = 5.5V$
		C ₁₄ -C ₁₇	5.5	100	μА	$V_I = 5.5V$
I _{IL}	Maximum Input Current in LOW State	A ₉ –A ₁₃ , PLH _{IN} , HD, DIR, HLH _{IN}	5.5	-1.0	μΑ	$V_I = 0.0V$
		C ₁₄ -C ₁₇	5.5	-5.0	mA	$V_I = 0.0V$
I _{OZH}	Maximum Output Disable Current	A ₁ —A ₈	5.5	20	μА	V _O = 5.5V
	(HIGH)	B ₁ -B ₈	5.5	100	μА	$V_O = 5.5V$
I _{OZL}	Maximum Output Disable Current	A ₁ —A ₈	5.5	-20	μΑ	V _O = 0.0V
	(LOW)	B ₁ -B ₈	5.5	-5.0	mA	
I _{OFF}	Power Down Output Leakage	B ₁ -B ₈ , Y ₉ -Y ₁₃ , PLH	0.0	100	μΑ	V _O = 5.5V
I _{OFF}	Power Down Input Leakage	C ₁₄ -C ₁₇ , HLH _{IN}	0.0	100	μΑ	$V_I = 5.5V$
I _{OFF} – I _{CC}	Power Down Leakage to V _{CC}		0.0	250	μΑ	(Note 7)
I _{CC}	Maximum Supply Current		5.5	70	mA	$V_I = V_{CC}$ or GND

Note 5: Output impedance is measured with the output active LOW and active HIGH (HD = HIGH).

Note 6: This parameter is guaranteed but not tested, characterized only.

Note 7: Power-down leakage to V_{CC} is tested by simultaneously forcing all pins on the cable-side (B₁-B₈, Y_9 - Y_{13} , PLH, C_{14} - C_{17} and HLH_{IN} to 5.5V and measuring the resulting I_{CC} .

AC Electrical Characteristics

		T _A = -40°	°C to +85°C		
Symbol	Parameter	V _{CC} = 4	.5V – 5.5V	Units	Figure Number
		Min	Max		
t _{PHL}	A ₁ -A ₈ to B ₁ -B ₈	2.0	30.0	ns	Figure 1
t _{PLH}	A_1 - A_8 to B_1 - B_8	2.0	30.0	ns	Figure 2
t _{PHL}	B ₁ -B ₈ to A ₁ -A ₈	2.0	30.0	ns	Figure 3
t _{PLH}	B ₁ -B ₈ to A ₁ -A ₈	2.0	30.0	ns	Figure 3
t _{PHL}	A ₉ -A ₁₃ to Y ₉ -Y ₁₃	2.0	30.0	ns	Figure 1
t _{PLH}	A ₉ -A ₁₃ to Y ₉ -Y ₁₃	2.0	30.0	ns	Figure 2
t _{PHL}	C ₁₄ -C ₁₇ to A ₁₄ -A ₁₇	2.0	30.0	ns	Figure 3
t _{PLH}	C ₁₄ -C ₁₇ to A ₁₄ -A ₁₇	2.0	30.0	ns	Figure 3
t _{SKEW}	LH-LH or HL-HL		6.0	ns	(Note 9)
t _{PHL}	PLH _{IN} to PLH	2.0	30.0	ns	Figure 1
t _{PLH}	PLH _{IN} to PLH	2.0	30.0	ns	Figure 2
t _{PHL}	HLH _{IN} to HLH	2.0	30.0	ns	Figure 3
t _{PLH}	HLH _{IN} to HLH	2.0	30.0	ns	Figure 3
t _{PHZ}	Output Disable Time	2.0	18.0		Figure 7
t_{PLZ}	DIR to A ₁ -A ₈	2.0	18.0	ns	
t _{PZH}	Output Enable Time	2.0	25.0	ns	Figure 8
t_{PZL}	DIR to A ₁ -A ₈	2.0	25.0	115	
t _{PHZ}	Output Disable Time	2.0	25.0	ns	Figure 9
t_{PLZ}	DIR to B ₁ -B ₈	2.0	25.0	115	
t _{pEN}	Output Enable Time	2.0	28.0	200	Figure 2
	HD to B ₁ -B ₈ , Y ₉ -Y ₁₃	2.0	26.0	ns	
t _{pDis}	Output Disable Time	2.0	28.0	ns	Figure 2
	HD to B ₁ -B ₈ , Y ₉ -Y ₁₃	2.0	26.0	115	Figure 2
t _{pEn} -t _{pDis}	Output Enable-Output Disable		20.0	ns	
t _{SLEW}	Output Slew Rate				
t _{PLH}	B ₁ -B ₈ , Y ₉ -Y ₁₃	0.05	0.40	V/ns	Figure 5
t _{PHL}		0.05	0.40	v/IIS	Figure 4
t _r , t _f	t _{RISE} and t _{FALL}		120	20	Figure 6
	B ₁ -B ₈ , Y ₉ -Y ₁₃ (Note 8)		120	ns	(Note 10)

Note 8: Open Drain

 $\textbf{Note 9: } t_{\text{SKEW}} \text{ is measured for common edge output transitions and compares the measured propagation delay for a given path type.} \\$

(i) A_1 - A_8 to B_1 - B_8 , A_9 - Y_{13} to Y_9 - Y_{13}

(ii) B₁-B₈ to A₁-A₈

(iii) C₁₄-C₁₇ to A₁₄-A₁₇

Note 10: This parameter is guaranteed but not tested, characterized only.

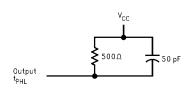
Capacitance (Note 11)

Symbol	Parameter	Тур	Units	Conditions
C _{IN}	Input Capacitance	5	pF	$V_{CC} = 0.0V \text{ (HD, DIR, A}_9 - A_{13}, C_{14} - C_{17}, PLH_{IN} \text{ and HLH}_{IN})$
C _{I/O}	I/O Pin Capacitance	12	pF	V _{CC} = 3.3V

Note 11: Capacitance is measured at frequency = 1 MHz.

AC Loading and Waveforms

Pulse Generator for all pulses: Rate \leq 1.0 MHz; $Z_0 \leq$ 50 Ω ; $t_f \leq$ 2.5 ns, $t_r \leq$ 2.5 ns.



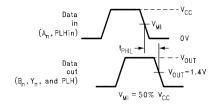
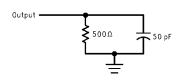
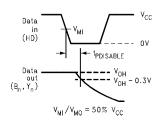
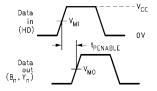


FIGURE 1. t_{PHL} Test Load and Waveforms A_1-A_8 to B_1-B_8 A_9-A_{13} to Y_9-Y_{13} PLH $_{IN}$ to PLH







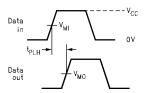
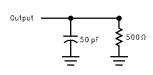


FIGURE 2. t_{PLH} , t_{pEn} , t_{pDis} Test Load and Waveforms A_1-A_8 to B_1-B_8 , A_9-A_{13} to Y_9-Y_{13} PLH_{IN} to PLH, HD to B_1-B_8 , Y_9-Y_{13} , PLH



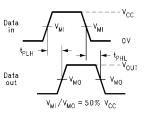
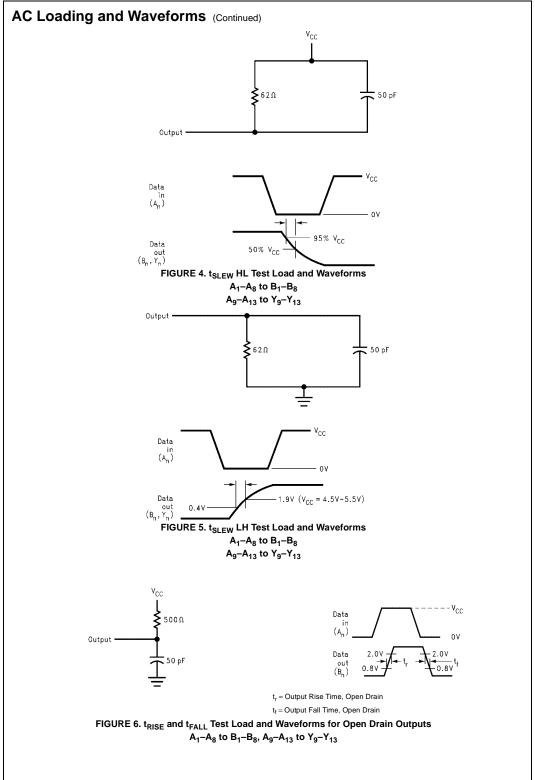
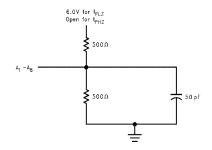
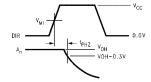


FIGURE 3. t_{PHL} , t_{PLH} Test Load and Waveforms B₁–B₈ to A₁–A₈, C₁₄–C₁₇ to A₁₄–A₁₇, HLH_{IN} to HLH



AC Loading and Waveforms (Continued)





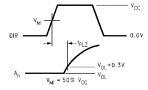
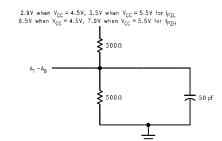
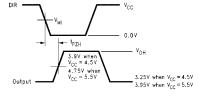


FIGURE 7. $t_{\mbox{\scriptsize PHZ}}$ and $t_{\mbox{\scriptsize PLZ}}$ Test Load and Waveforms, DIR to $A_1\text{--}A_8$





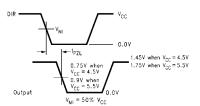
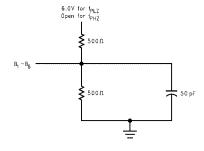
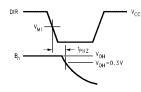


FIGURE 8. $t_{\mbox{\scriptsize PZH}}$ and $t_{\mbox{\scriptsize PZL}}$ Test Load and Waveforms, DIR to $\mbox{A}_{\mbox{\scriptsize 1}}\mbox{-}\mbox{A}_{\mbox{\scriptsize 8}}$

AC Loading and Waveforms (Continued)





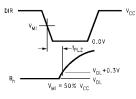
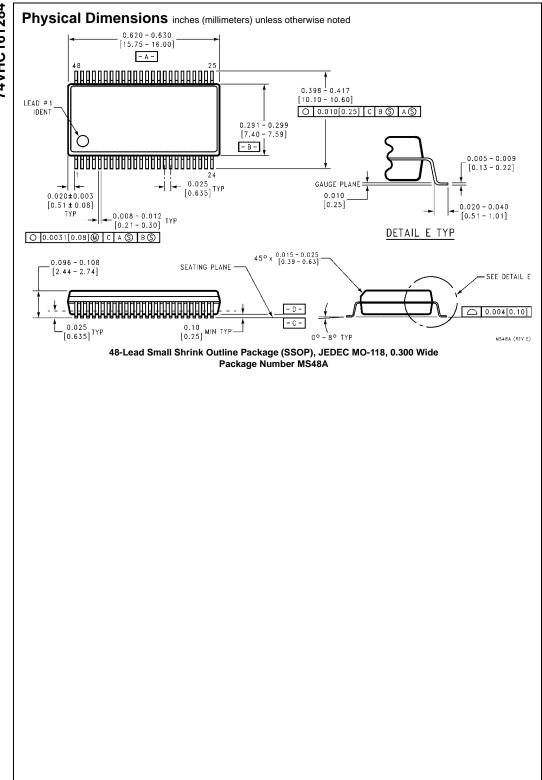
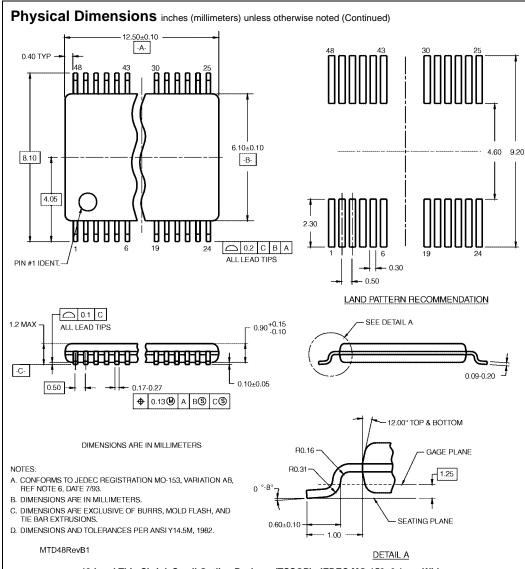


FIGURE 9. t_{PHZ} and t_{PLZ} Test Load and Waveforms, DIR to $\text{B}_1\text{--}\text{B}_8$





48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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